

PHOTOCOUPLER

PS2501-1,-2,-4,PS2501L-1,-2,-4

HIGH ISOLATION VOLTAGE SINGLE TRANSISTOR TYPE MULTI PHOTOCOUPLER SERIES

-NEPOC Series-

DESCRIPTION

The PS2501-1, -2, -4 and PS2501L-1, -2, -4 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor.

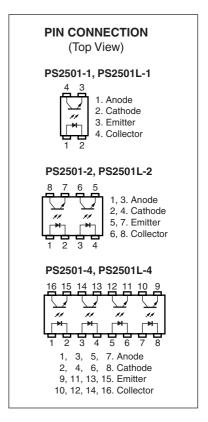
The PS2501-1, -2, -4 are in a plastic DIP (Dual In-line Package) and the PS2501L-1, -2, -4 are lead bending type (Gull-wing) for surface mount.

FEATURES

- High isolation voltage (BV = 5 000 Vr.m.s.)
- High collector to emitter voltage (VCEO = 80 V)
- High-speed switching ($t_r = 3 \mu s TYP$., $t_f = 5 \mu s TYP$.)
- Ordering number of tape product: PS2501L-1-E3, E4, F3, F4, PS2501L-2-E3, E4
- · Safety standards
 - UL approved: File No. E72422

APPLICATIONS

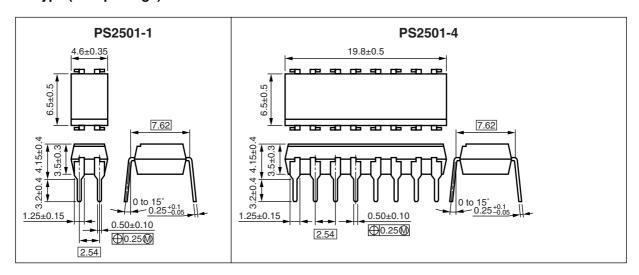
- Power supply
- · Telephone/FAX.
- FA/OA equipment
- Programmable logic controller



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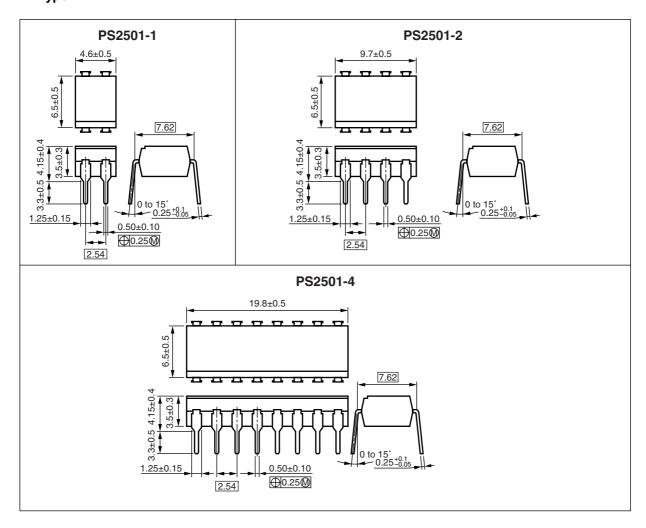
PACKAGE DIMENSIONS (UNIT: mm)

DIP Type (New package)

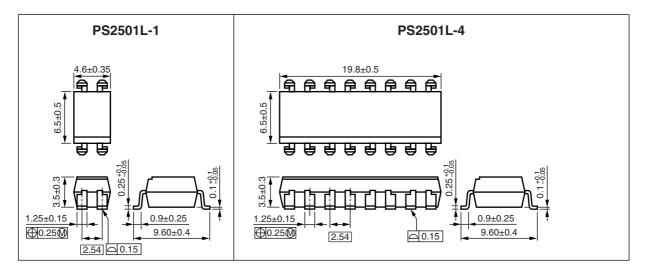


Caution New package 1-ch, 4-ch only

DIP Type

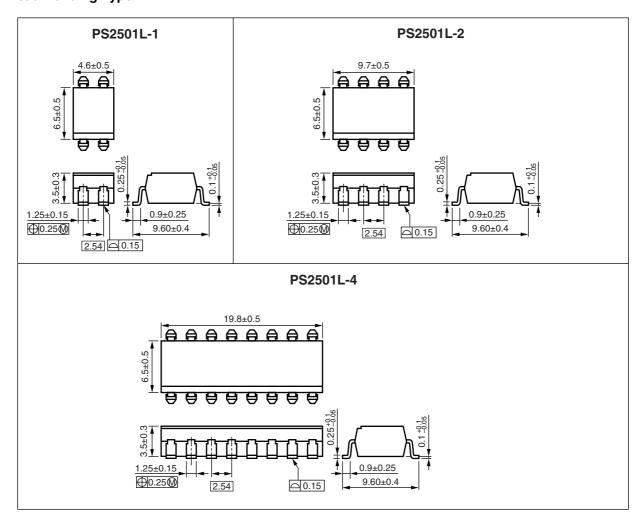


Lead Bending Type (New package)

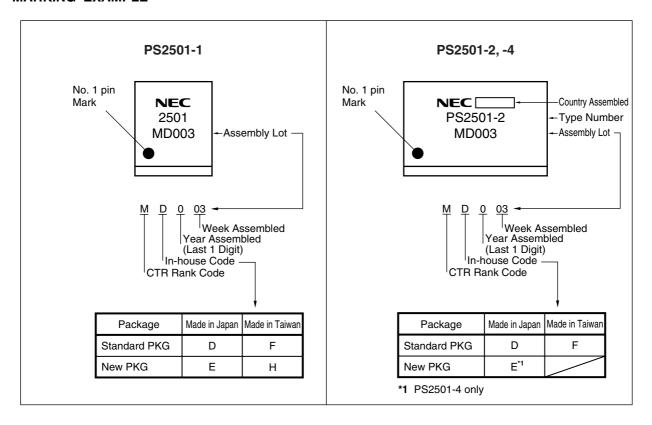


Caution New package 1-ch, 4-ch only

Lead Bending Type



MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS2501-1	PS2501-1	Solder	Magazine case 100 pcs	Standard products	PS2501-1
PS2501L-1	PS2501L-1	contains lead		(UL Approved)	
PS2501L-1-E3	PS2501L-1-E3		Embossed Tape 1 000 pcs/reel		
PS2501L-1-E4	PS2501L-1-E4				
PS2501L-1-F3	PS2501L-1-F3		Embossed Tape 2 000 pcs/reel		
PS2501L-1-F4	PS2501L-1-F4				
PS2501-2	PS2501-2		Magazine case 45 pcs		PS2501-2
PS2501L-2	PS2501L-2				
PS2501L-2-E3	PS2501L-2-E3		Embossed Tape 1 000 pcs/reel		
PS2501L-2-E4	PS2501L-2-E4				
PS2501-4	PS2501-4		Magazine case 20 pcs		PS2501-4
PS2501L-4	PS2501L-4				
PS2501-1	PS2501-1-A	Pb-Free	Magazine case 100 pcs		PS2501-1
PS2501L-1	PS2501L-1-A				
PS2501L-1-E3	PS2501L-1-E3-A		Embossed Tape 1 000 pcs/reel		
PS2501L-1-E4	PS2501L-1-E4-A				
PS2501L-1-F3	PS2501L-1-F3-A		Embossed Tape 2 000 pcs/reel		
PS2501L-1-F4	PS2501L-1-F4-A				
PS2501-2	PS2501-2-A		Magazine case 45 pcs		PS2501-2
PS2501L-2	PS2501L-2-A				
PS2501L-2-E3	PS2501L-2-E3-A		Embossed Tape 1 000 pcs/reel		
PS2501L-2-E4	PS2501L-2-E4-A				
PS2501-4	PS2501-4-A		Magazine case 20 pcs		PS2501-4
PS2501L-4	PS2501L-4-A				

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (Unless otherwise specified, T_A = 25°C)

		Ratings			
Parameter		Symbol	PS2501-1, PS2501L-1	PS2501-2,-4 PS2501L-2,-4	Unit
Diode	Reverse Voltage	VR	6		V
	Forward Current (DC)		80		mA
	Power Dissipation Derating	⊿P₀/°C	1.5	1.2	mW/°C
	Power Dissipation	Po	150	120	mW/ch
	Peak Forward Current [™]	I FP		1	
Transistor	Collector to Emitter Voltage	Vceo	80		V
	Emitter to Collector Voltage	VECO	7		V
	Collector Current	lc	50		mA/ch
	Power Dissipation Derating	⊿Pc/°C	1.5	1.2	mW/°C
	Power Dissipation	Pc	150	120	mW/ch
Isolation Voltage ^{*2}		BV	5 000		Vr.m.s.
Operating Ambient Temperature		TA	-55 to +100		°C
Storage Temperature		Tstg	-55 to +150		°C

^{*1} PW = 100 μ s, Duty Cycle = 1%

^{*2} AC voltage for 1 minute at $T_A = 25^{\circ}C$, RH = 60% between input and output.

Pins 1-2 shorted together, 3-4 shorted together (PS2501-1, PS2501L-1).

Pins 1-4 shorted together, 5-8 shorted together (PS2501-2, PS2501L-2).

Pins 1-8 shorted together, 9-16 shorted together (PS2501-4, PS2501L-4).

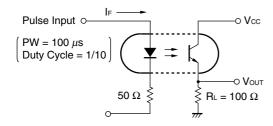
ELECTRICAL CHARACTERISTICS (TA = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.17	1.4	V
	Reverse Current	IR	V _R = 5 V			5	μΑ
	Terminal Capacitance	Ct	V = 0 V, f = 1.0 MHz		50		pF
Transistor	Collector to Emitter Dark Current	Iceo	VcE = 80 V, IF = 0 mA			100	nA
Coupled	Current Transfer Ratio	CTR	IF = 5 mA, VcE = 5 V	80	300	600	%
	Collector Saturation Voltage	VCE(sat)	IF = 10 mA, Ic = 2 mA			0.3	٧
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time ^{*2}	tr	Vcc = 10 V, Ic = 2 mA, RL = 100 Ω		3		μs
	Fall Time ^{*2}	tr			5		

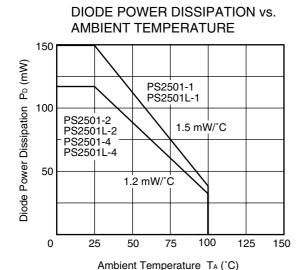
*1 CTR rank (*: only PS2501-1, PS2501L-1)

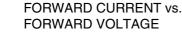
K*: 300 to 600 (%)
L*: 200 to 400 (%)
M*: 80 to 240 (%)
D*: 100 to 300 (%)
H*: 80 to 160 (%)
W*: 130 to 260 (%)
Q*: 100 to 200 (%)
N: 80 to 600 (%)

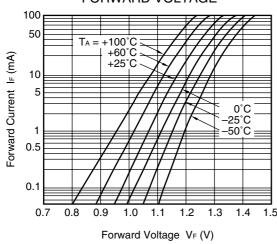
*2 Test circuit for switching time



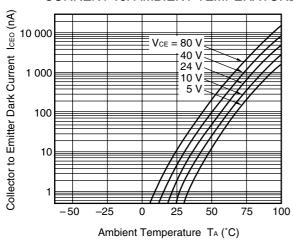
TYPICAL CHARACTERISTICS (Unless otherwise specified, TA = 25°C)



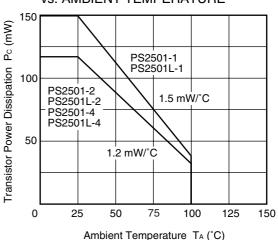




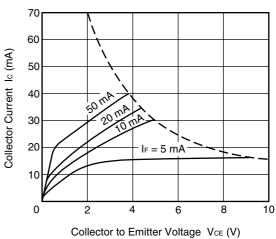
COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE



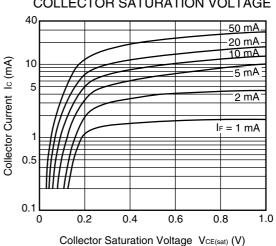
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE

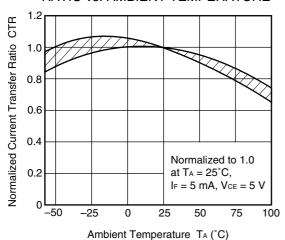


COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE

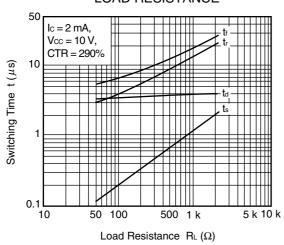


Remark The graphs indicate nominal characteristics.

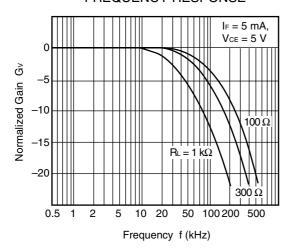
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



SWITCHING TIME vs. LOAD RESISTANCE

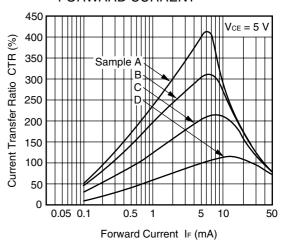


FREQUENCY RESPONSE

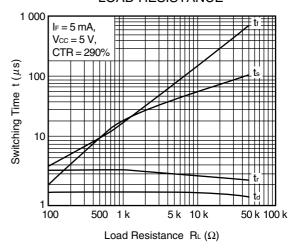


Remark The graphs indicate nominal characteristics.

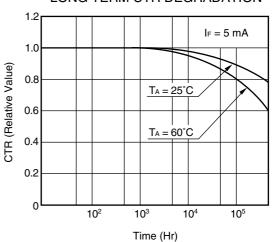
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



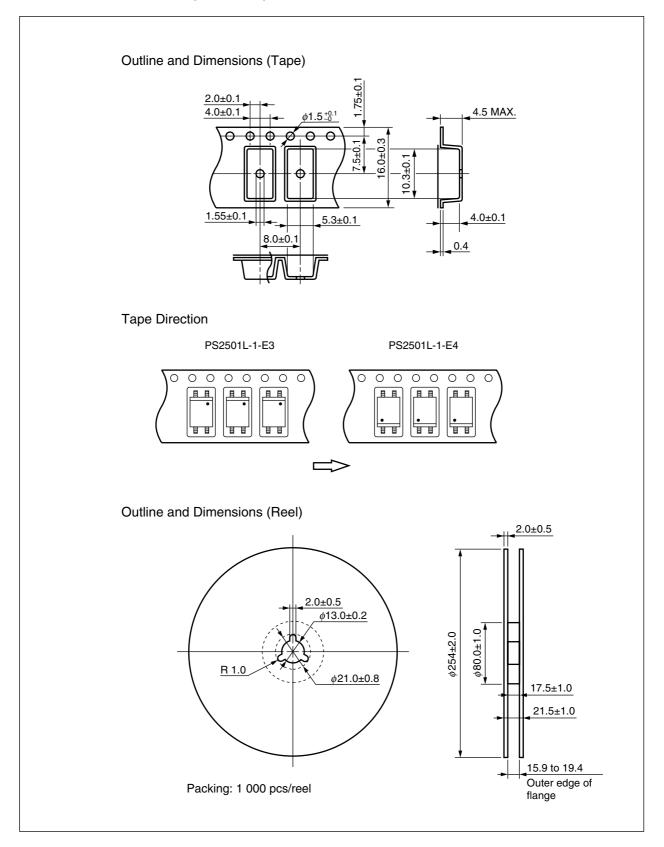
SWITCHING TIME vs. LOAD RESISTANCE

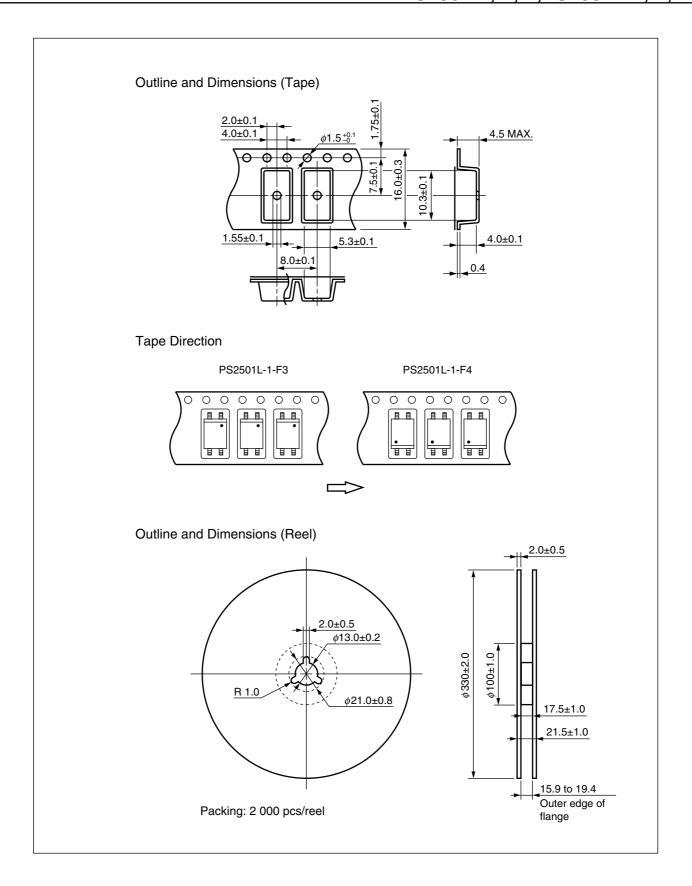


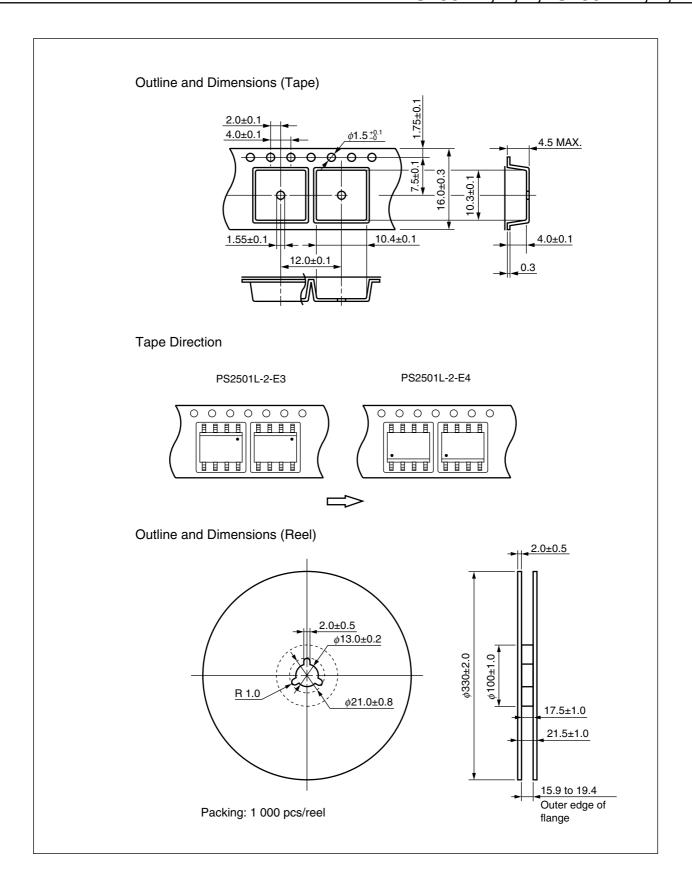
LONG TERM CTR DEGRADATION



TAPING SPECIFICATIONS (UNIT: mm)







NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

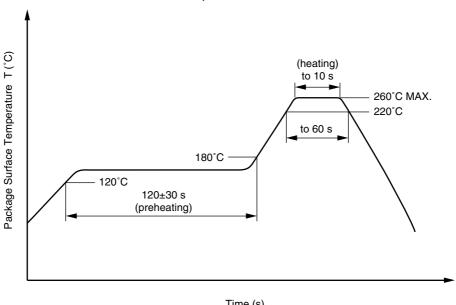
• Time of peak reflow temperature 10 seconds or less • Time of temperature higher than 220°C 60 seconds or less

• Time to preheat temperature from 120 to 180°C 120±30 s · Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

 Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

· Preheating conditions 120°C or below (package surface temperature)

· Number of times One (Allowed to be dipped in solder including plastic mold portion.)

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

• Peak temperature (lead part temperature) 350°C or below • Time (each pins) 3 seconds or less

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- **2.** Avoid storage at a high temperature and high humidity.

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M8E 00.4-0110

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

NEC Compound Semiconductor Devices, Ltd. http://www.ncsd.necel.com/

E-mail: salesinfo@ml.ncsd.necel.com (sales and general) techinfo@ml.ncsd.necel.com (technical)

Sales Division TEL: +81-44-435-1588 FAX: +81-44-435-1579

NEC Compound Semiconductor Devices Hong Kong Limited

E-mail: ncsd-hk@elhk.nec.com.hk (sales, technical and general)

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309 Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859 Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

NEC Electronics (Europe) GmbH http://www.ee.nec.de/

TEL: +49-211-6503-0 FAX: +49-211-6503-1327

California Eastern Laboratories, Inc. http://www.cel.com/

TEL: +1-408-988-3500 FAX: +1-408-988-0279